

STC03DE170HV

Features

V _{CS(ON)}	۱ _C	R _{CS(ON)}
1 V	3 A	0.33 Ω

- Low equivalent on resistance
- Very fast-switch, up to 150 kHz
- Squared RBSOA, up to 1700V
- Very low C_{ISS} driven by $R_G = 47 \Omega$

Applications

■ Aux SMPS for three phase mains

Description

The STC03DE170HV is manufactured in a hybrid structure, using dedicated high voltage Bipolar and low voltage MOSFET technologies, aimed to providing the best performance in ESBT topology. The STC03DE170HV is designed for use in aux flyback smps for any three phase application.

Applications

Aux SMPS for three phase mains

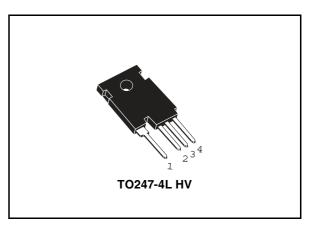


Figure 1. Internal schematic diagrams

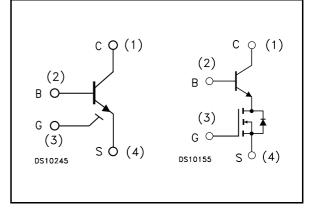


Table 1.Device summary

Order code	code Marking Package		Packaging	
STC03DE170HV	C03DE170HV	TO247-4L HV	Tube	

1 Electrical ratings

Table 2.	Absolute maximum ratings
Table 2.	Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CS(SS)}	Collector-source voltage (V _{BS} =V _{GS} =0V)	1700	V
V _{BS(OS)}	Base-source voltage (I _C =0, V _{GS} =0V)	30	V
V _{SB(OS)}	Source-base voltage (I _C =0, V _{GS} =0V)	9	V
V_{GS}	Gate-source voltage	±20	V
۱ _C	Collector current	3	А
I _{CM}	Collector peak current (t _P < 5ms)	6	А
Ι _Β	Base current	1	А
I _{BM}	Base peak current (t _P < 1ms)	3	А
P _{tot}	Total dissipation at $T_c \le 25^{\circ}C$	100	W
T _{stg}	Storage temperature	-40 to 150	°C
Т _Ј	Max. operating junction temperature	125	°C

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max	1	°C/W

2 Electrical characteristics

($T_{case} = 25^{\circ}C$ unless otherwise specified)

Table 4.	Electrical	characteristics
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Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{CS(SS)}	Collector-source current $(V_{BS} = V_{GS} = 0V)$	V _{CS(SS)} =1700V			100	μA
I _{BS(OS)}	Base-source current (I _C =0, V _{GS} =0V)	V _{BS(OS)} =30V			10	μA
I _{SB(OS)}	Source-base current (I _C =0, V _{GS} =0V)	V _{SB(OS)} =9V			100	μA
I _{GS(OS)}	Gate-source leakage (V _{BS} =0V)	$V_{GS} = \pm 20V$			500	nA
V _{CS(ON)}	Collector-source ON voltage	$V_{GS} = 10V I_{C} = 3A I_{B} = 0.6A$ $V_{GS} = 10V I_{C} = 1A I_{B} = 100mA$		1 0.3	1.2 0.6	V V
h _{FE}	DC current gain	$V_{GS} = 10V V_{CS} = 1V I_{C} = 3A$ $V_{GS} = 10V V_{CS} = 1V I_{C} = 1A$	10	5 14		
V _{BS(ON)}	Base-source ON voltage	$V_{GS} = 10V I_C = 3A I_B = 0.6A$ $V_{GS} = 10V I_C = 1A I_B = 100mA$		1 1	1.2	V V
V _{GS(th)}	Gate threshold voltage	V _{BS} =V _{GS} I _B =250μA	1.5		3	V
C _{iss}	Input capacitance	V _{CS} =25V f =1MHz V _{GS} =0V		750		pF
Q _{GS(tot)}	Gate-source Charge	V_{CS} =15V V_{GS} =10V V_{CB} =0V I_{C} =4A		12.5		nC
t _s t _f	INDUCTIVE LOAD Storage time Fall time	$\label{eq:VGS} \begin{array}{ll} V_{GS} = \! 10V & R_G = \! 47\Omega \\ V_{Clamp} = \! 1360V & t_p = \! 4\mu s \\ I_C = \! 3A & I_B = \! 0.6A \end{array}$		1000 15		ns ns
t _s t _f	INDUCTIVE LOAD Storage time Fall time	$\label{eq:VGS} \begin{array}{ll} V_{GS} = \! 10V & R_G = \! 47\Omega \\ V_{Clamp} = \! 1360V & t_p = \! 4\mu s \\ I_C = \! 3A & I_B = \! 0.3A \end{array}$		590 15		ns ns
V _{CS(dyn)}	Collector-source dynamic voltage (500ns)	$\label{eq:V_CC} \begin{split} &V_{CC} = V_{Clamp} = 400 V \\ &V_{GS} = 10 V \qquad I_C = 1.5 A \\ &I_B = 0.1 A \qquad R_G = 47 \Omega \\ &t_{peak} = 500 ns \qquad I_{Bpeak} = 3 A \end{split}$		9.5		V



Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{CS(dyn)}	Collector-source dynamic voltage (1µs)	$V_{CC} = V_{Clamp} = 400V$ $V_{GS} = 10V \qquad I_C = 1.5A$ $I_B = 0.1A \qquad R_G = 47\Omega$ $t_{peak} = 500ns \qquad I_{Bpeak} = 3A$		9.5		v
V _{CSW}	Maximum collector- source voltage switched without snubber	$R_{G} = 47\Omega$ $h_{FE} = 5$ $I_{C} = 4A$	1700			V

Table 4. Electrical characteristics

Note (1) Pulsed duration = 300 μ s, duty cycle \leq 1.5%

Output characteristics

2.1 Electrical characteristics (curves)

Figure 2.

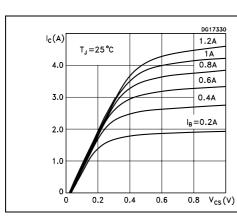


Figure 3. Dynamic collector-source saturation voltage

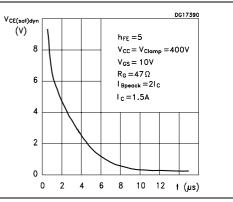
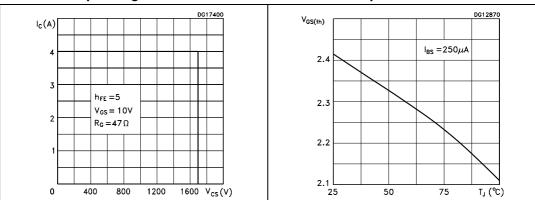


Figure 4.Reverse biased safeFigure 5.Gate threshold voltage vsoperating areatemperature





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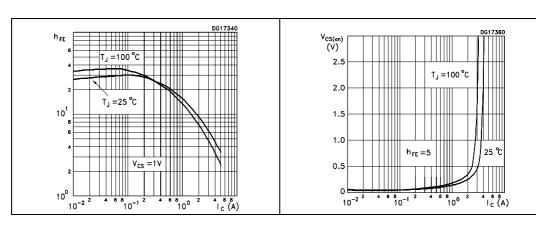


Figure 8. Collector-source On voltage Figure 9. Base-source On voltage

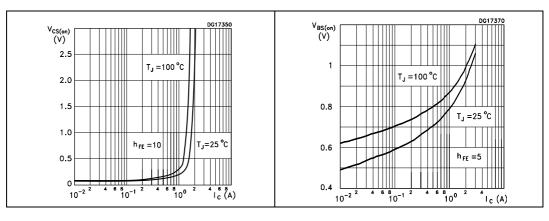


Figure 10. Inductive load switching time Figure 11. Inductive load switching time

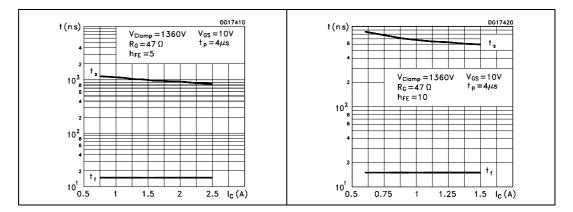


Figure 6. DC current gain

Figure 7. Collector-source On voltage

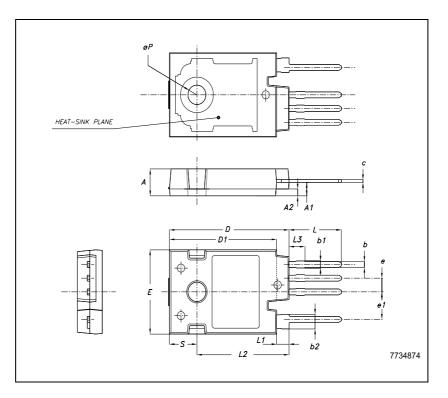
3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



DIM.		mm.	
	MIN.	ТҮР	MAX.
A	4.85		5.15
A1	2.20	2.50	2.60
A2		1.27	
b	0.95	1.10	1.30
b2	2.50		2.90
С	0.40		0.80
D	23.85	24	24.15
D1		21.50	
E	15.45	15.60	15.75
е	2.54		
e1	5.08		
L	10.20		10.80
L1	2.20	2.50	2.80
L2		18.50	
L3		3	
øP	3.55		3.65
S		5.50	







4 Revision history

Table 5.	Revision	hietory
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Date	Revision	Changes
26-Sep-2006	1	First release.
12-Jul-2007	2	Improved electrical specification. Updated figures: 2,3,4,6,7,8,9,10 and 11.



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